

Docket No.: 50090-318

PATENT

IN THE UNITED STATES PATENT AND TRADEMARK OFFICE

In re Application of

Yoshifumi TAKATA, et al.

Serial No.: 09/903,760

Filed: July 13, 2001

Group Art Unit: 2822

Examiner: J. Mitchell

For: SEMICONDUCTOR DEVICE HAVING AN IMPROVED INTERLAYER
CONDUCTOR CONNECTIONS AND A MANUFACTURING METHOD
THEREOF

AMENDMENT

Commissioner for Patents
Washington, DC 20231

Sir:

The following Amendment and Remarks are submitted in response to the Office
Action dated October 16, 2002.

IN THE CLAIMS:

Please amend claim 9 as follows.

9. (Twice Amended) A method of manufacturing a semiconductor device
comprising the steps of sequentially:

forming a first interlayer insulating film on a semiconductor substrate;

forming a plurality of openings in said first interlayer insulating film;

forming a conductor film on said first interlayer insulating film so as to fill said
openings;

